

A

B

C

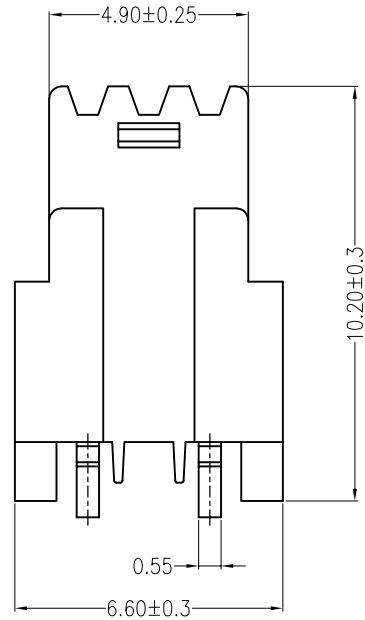
D

E

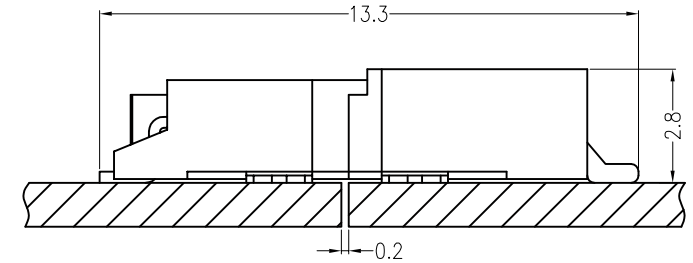
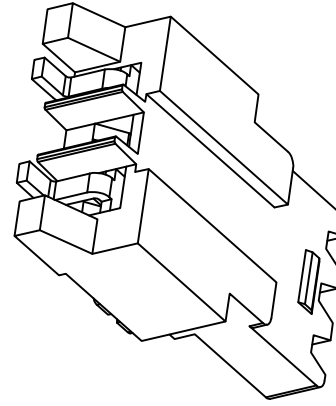
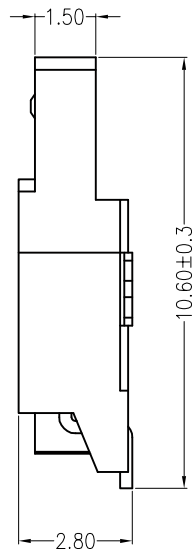
F

REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2015.07.15

1



2



1

Assembly Layout

Main Specifications

Poles: 02

Contact resistance: $\leq 20\text{m}\Omega$

Insulation resistance: $\geq 1000\text{M}\Omega$

Rated voltage: 150V AC DC

Rated current: 1.0A AC DC

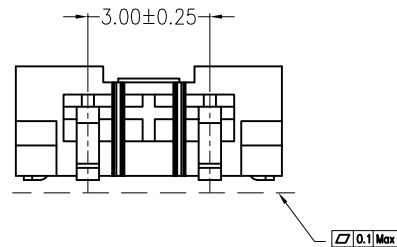
Withstand Voltage: 1000V AC/minute

Temperature Range: -25°C --- $+105^{\circ}\text{C}$

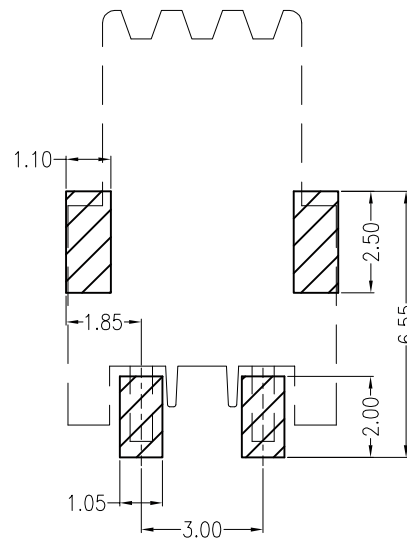
2

3

4



5



Board Layout

General Tolerance: ± 0.05



3

4

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn

TITLE: --
3.0mmPITCH 90°WAFER SMT TYPE

X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°		APPD: 邵敬和	DWG NO.:
.XX±0.25	.XX±1°	CHKD: 田峰	SCALE	
--	--	DR: 吴丹平	1 : 1	SHEET
UNITS: mm				1 / 1

A

B

C

D

E

F